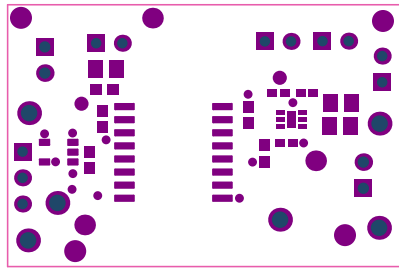
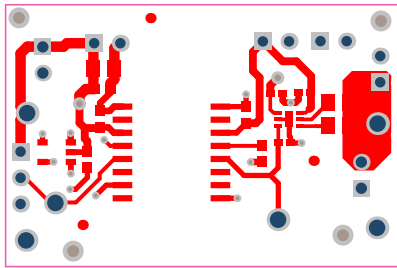


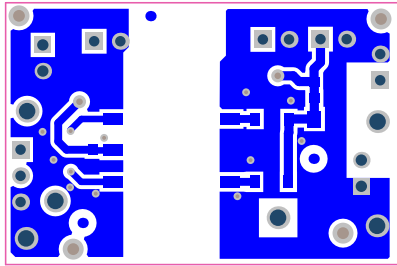
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:ISO-GaN-Driver	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-00785		
PLOT NAME = Top Overlay	GENERATED : 3/23/2016	1:10:27 PM	TEXAS INSTRUMENTS



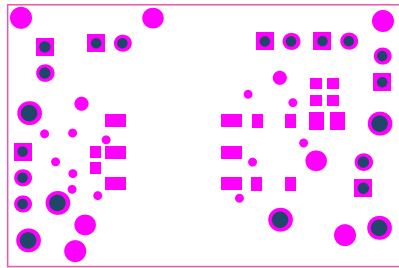
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:ISO-GaN-Driver	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-00785		
PLOT NAME = Top Solder Mask	GENERATED : 3/23/2016 1:10:28 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:ISO-GaN-Driver	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-00785		
PLOT NAME = Top Layer	GENERATED : 3/23/2016 1:10:28 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:ISO-GaN-Driver	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-00785		
PLOT NAME = Bottom Layer	GENERATED : 3/23/2016 1:10:29 PM	TEXAS INSTRUMENTS	

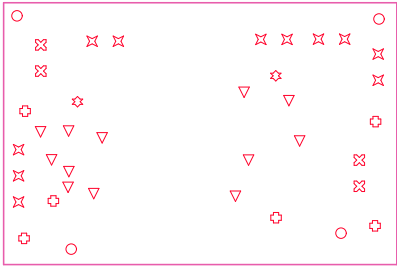


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:ISO-GaN-Driver	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-00785		
PLOT NAME = Bottom Solder Mask	GENERATED : 3/23/2016 1:10:29 PM	TEXAS INSTRUMENTS	

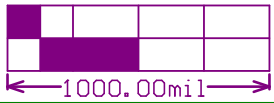
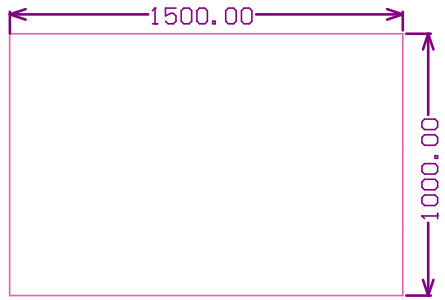


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: ISO-GaN-Driver	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-00785		
PLOT NAME = Bottom Overlay	GENERATED : 3/23/2016	1:10:30 PM	TEXAS INSTRUMENTS

Symbol	Quantity	Finished Hole Size	Plated	Hole Type
◇	18	15.00mil (0.381mm)	PTH	Round
	18 Total			



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:ISO-GaN-Driver	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-00785		
PLOT NAME = Drill Drawing	GENERATED : 3/23/2016 1:10:30 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:ISO-GaN-Driver	REV: E1	SVN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-00785		
PLOT NAME = Board Dimensions	GENERATED : 3/23/2016 1:10:31 PM	TEXAS INSTRUMENTS	



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